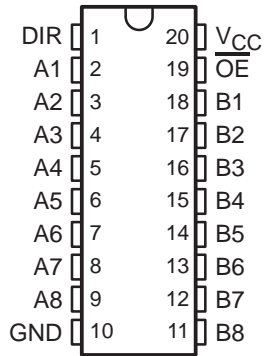


# SN54HC245, SN74HC245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

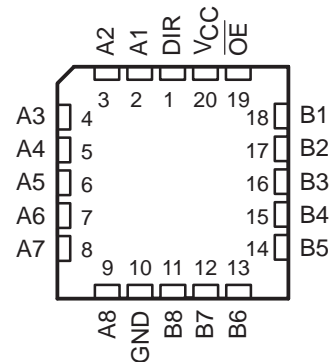
SCLS131D – DECEMBER 1982 – REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 12$  ns
- $\pm 6$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max

SN54HC245 . . . J OR W PACKAGE  
SN74HC245 . . . DB, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54HC245 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74HC245N	SN74HC245N
	SOIC – DW	Tube of 25	SN74HC245DW	HC245
		Reel of 2000	SN74HC245DWR	
	SOP – NS	Reel of 2000	SN74HC245NSR	HC245
	SSOP – DB	Reel of 2000	SN74HC245DBR	HC245
	TSSOP – PW	Tube of 70	SN74HC245PW	HC245
Reel of 2000		SN74HC245PWR		
Reel of 250		SN74HC245PWT		
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54HC245J	SNJ54HC245J
	CFP – W	Tube of 85	SNJ54HC245W	SNJ54HC245W
	LCCC – FK	Tube of 55	SNJ54HC245FK	SNJ54HC245FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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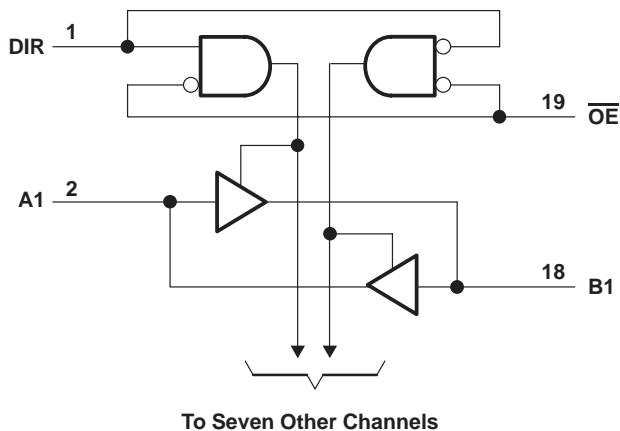
# SN54HC245, SN74HC245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54HC245, SN74HC245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 3)

		SN54HC245			SN74HC245			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V		1.5	1.5		V	
		V <sub>CC</sub> = 4.5 V		3.15	3.15			
		V <sub>CC</sub> = 6 V		4.2	4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5		0.5	V
		V <sub>CC</sub> = 4.5 V			1.35		1.35	
		V <sub>CC</sub> = 6 V			1.8		1.8	
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
Δt/Δv	Input transition rise/fall time	V <sub>CC</sub> = 2 V			1000		1000	ns
		V <sub>CC</sub> = 4.5 V			500		500	
		V <sub>CC</sub> = 6 V			400		400	
T <sub>A</sub>	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC245		SN74HC245		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = -6 mA	4.5 V	3.98	4.3		3.7		3.84		
			6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		V	
			4.5 V		0.001	0.1		0.1			0.1
			6 V		0.001	0.1		0.1			0.1
		I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4			0.33
			6 V		0.15	0.26		0.4			0.33
I <sub>I</sub>	DIR or $\overline{\text{OE}}$	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V		±0.1	±100		±1000		±1000	nA
I <sub>OZ</sub>	A or B	V <sub>O</sub> = V <sub>CC</sub> or 0	6 V		±0.01	±0.5		±10		±5	μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	6 V			8		160		80	μA
C <sub>i</sub>	DIR or $\overline{\text{OE}}$		2 V to 6 V		3	10		10		10	pF



**SN54HC245, SN74HC245**  
**OCTAL BUS TRANSCEIVERS**  
**WITH 3-STATE OUTPUTS**

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC245		SN74HC245		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	B or A	2 V		40	105	160		130		ns
			4.5 V		15	21	32		26		
			6 V		12	18	27		22		
$t_{en}$	$\overline{OE}$	A or B	2 V		125	230	340		290		ns
			4.5 V		23	46	68		58		
			6 V		20	39	58		49		
$t_{dis}$	$\overline{OE}$	A or B	2 V		74	200	300		250		ns
			4.5 V		25	40	60		50		
			6 V		21	34	51		43		
$t_t$		A or B	2 V		20	60	90		75		ns
			4.5 V		8	12	18		15		
			6 V		6	10	15		13		

switching characteristics over recommended operating free-air temperature range,  $C_L = 150 \text{ pF}$  (unless otherwise noted) (see Figure 1)

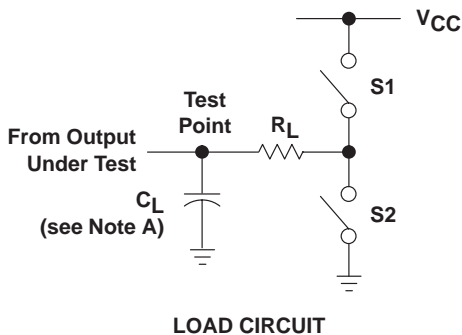
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC245		SN74HC245		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	B or A	2 V		54	135	200		170		ns
			4.5 V		18	27	40		34		
			6 V		15	23	34		29		
$t_{en}$	$\overline{OE}$	A or B	2 V		150	270	405		335		ns
			4.5 V		31	54	81		67		
			6 V		25	46	69		56		
$t_t$		A or B	2 V		45	210	315		265		ns
			4.5 V		17	42	63		53		
			6 V		13	36	53		45		

operating characteristics,  $T_A = 25^\circ\text{C}$

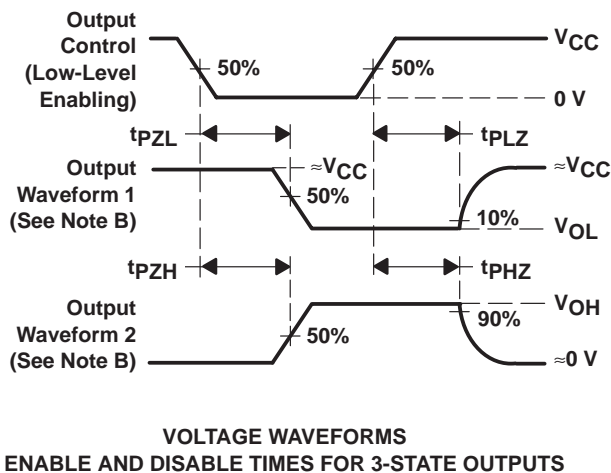
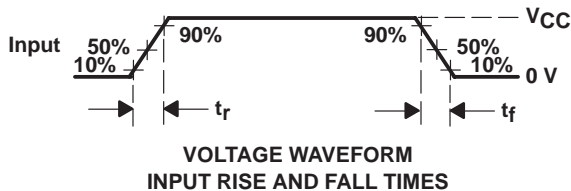
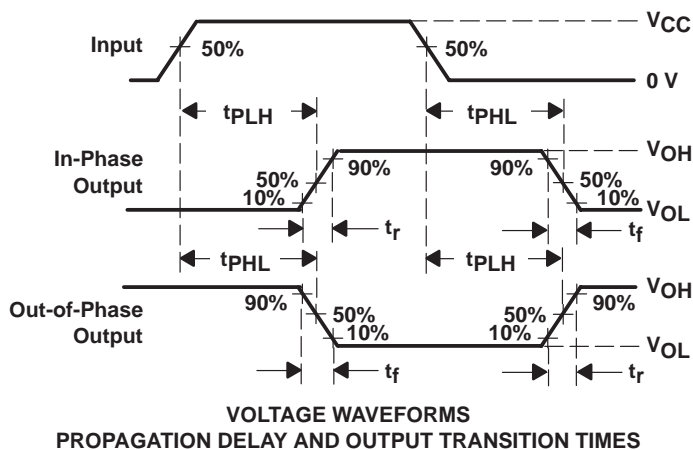
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per transceiver	No load	40	pF



PARAMETER MEASUREMENT INFORMATION



PARAMETER	$R_L$	$C_L$	S1	S2	
$t_{en}$	$t_{PZH}$	1 k $\Omega$	50 pF or 150 pF	Open	Closed
	$t_{PZL}$			Closed	Open
$t_{dis}$	$t_{PHZ}$	1 k $\Omega$	50 pF	Open	Closed
	$t_{PLZ}$			Closed	Open
$t_{pd}$ or $t_t$	—	50 pF or 150 pF	Open	Open	



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-8408501VRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
5962-8408501VSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
84085012A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
8408501RA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
8408501SA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65503BRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
JM38510/65503BSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
SN54HC245J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SN74HC245DBLE	OBSOLETE	SSOP	DB	20		None	Call TI	Call TI
SN74HC245DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC245DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74HC245DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74HC245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC245N3	OBSOLETE	PDIP	N	20		None	Call TI	Call TI
SN74HC245NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74HC245PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC245PWLE	OBSOLETE	TSSOP	PW	20		None	Call TI	Call TI
SN74HC245PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC245PWT	ACTIVE	TSSOP	PW	20	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54HC245FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC245J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SNJ54HC245W	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



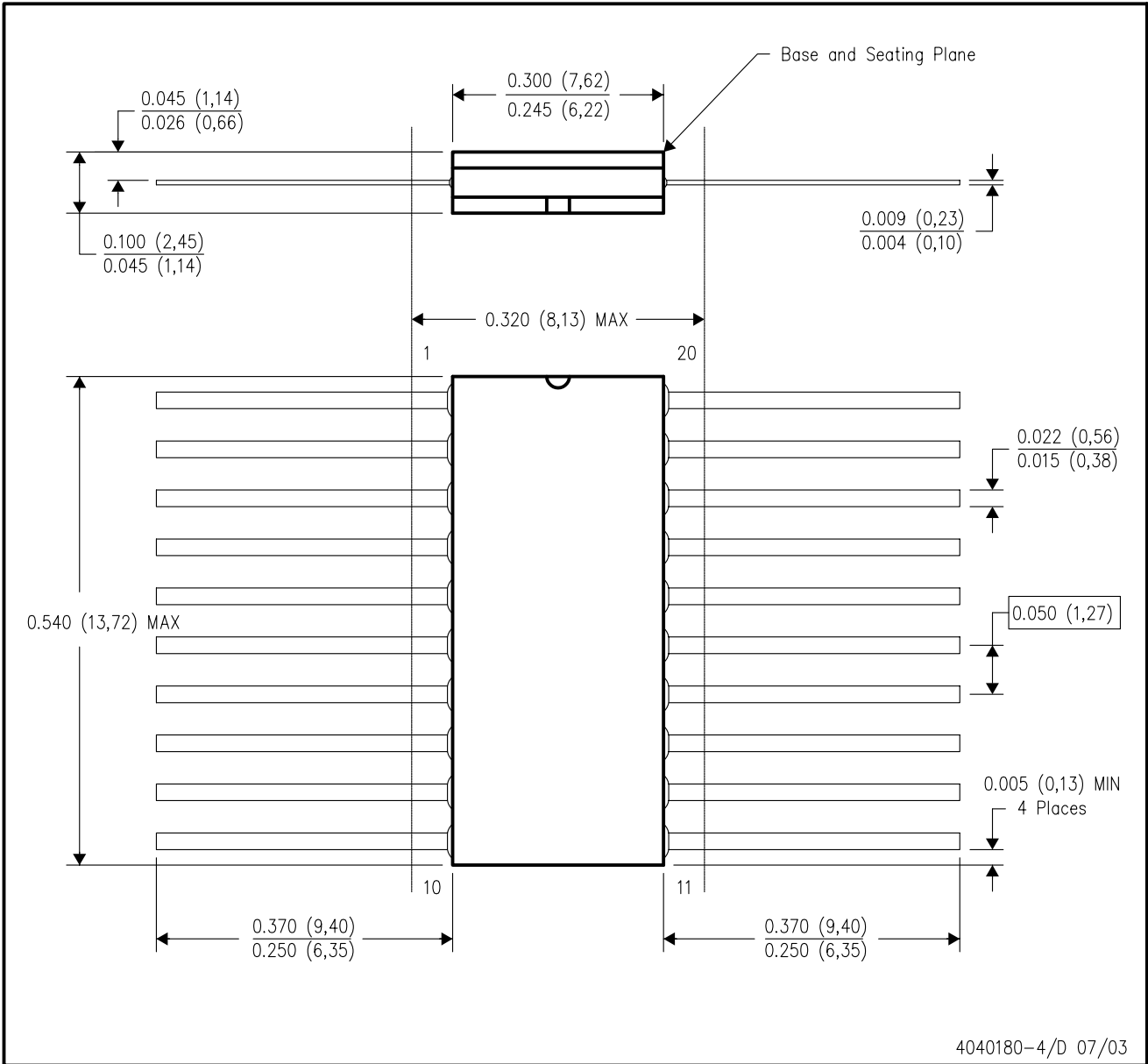
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



4040180-4/D 07/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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